Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **N. 1CP**
2. **N. 1R**
3. **1K**
4. **VCC**
5. **N. 2CP**
6. **N. 2R**
7. **2J**
8. **N. 2Q**
9. **2Q**
10. **2K**
11. **GND**
12. **1Q**
13. **N. 1Q**
14. **1J**

**.044”**

**2 1 14 13**

**12**

**11**

**10**

**9**

**3**

**4**

**5**

**6 7 8**

**HC 73T**

**MASK**

**REF**

**.053”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0035 x .0035”**

**Backside Potential: VCC or FLOAT**

**Mask Ref: HC73T**

**APPROVED BY: DK DIE SIZE .044” X .053” DATE: 3/19/20**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54HC73**

**DG 10.1.2**

#### Rev B, 7/1